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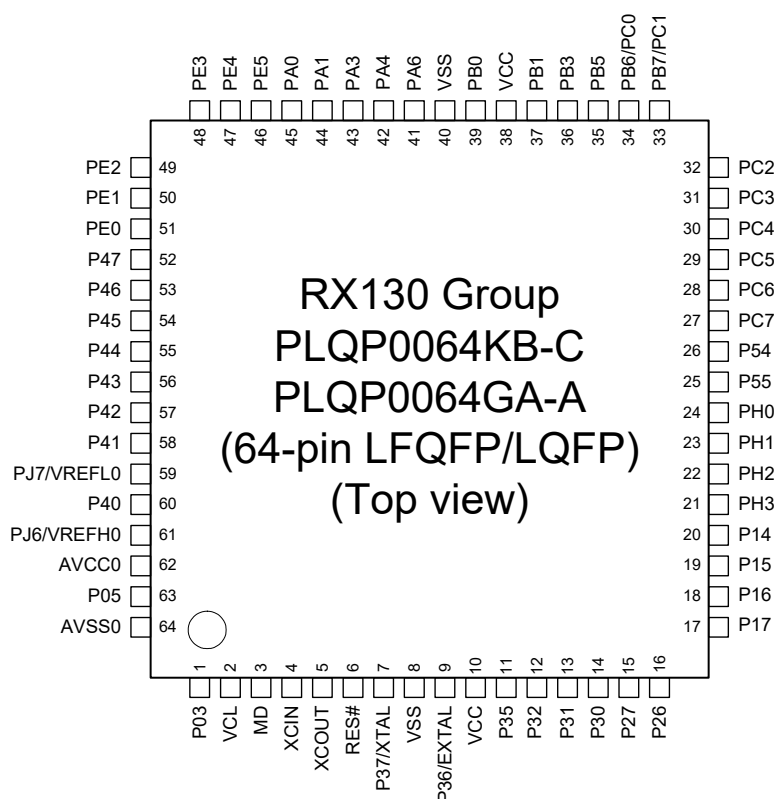
What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51305adfk-30



Note: This figure indicates the power supply pins and I/O ports.
 For the pin configuration, see the table "List of Pins and Pin Functions (64-Pin LFQFP/LQFP)".

Figure 1.5 Pin Assignments of the 64-Pin LFQFP/LQFP

Table 1.5 List of Pins and Pin Functions (100-Pin LFQFP) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIg, SC1h, RSPI, RIIC, REMC)	Touch sensing	Others
1		P06*1				
2		P03*1				DA0
3		P04*1				
4		PJ3	MTIOC3C	CTS6#/RTS6#/SS6#		
5	VCL					
6		PJ1	MTIOC3A			
7	MD					FINED
8	XCIN					
9	XCOUT					
10	RES#					
11	XTAL	P37				
12	VSS					
13	EXTAL	P36				
14	VCC					
15		P35				NMI
16		P34	MTIOC0A/TMC13/POE2#	SCK6		IRQ4
17		P33	MTIOC0D/TMRI3/POE3#	RXD6/SMISO6/SSCL6		IRQ3
18		P32	MTIOC0C/TMO3	TXD6/SMOSI6/SSDA6	TS0	IRQ2/RTCOUT
19		P31	MTIOC4D/TMC12	CTS1#/RTS1#/SS1#	TS1	IRQ1
20		P30	MTIOC4B/POE8#/TMRI3	RXD1/SMISO1/SSCL1	TS2	IRQ0
21		P27	MTIOC2B/TMC13	SCK1	TS3	
22		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1	TS4	
23		P25	MTIOC4C/MTCLKB			ADTRG0#
24		P24	MTIOC4A/MTCLKA/TMRI1			
25		P23	MTIOC3D/MTCLKD	CTS0#/RTS0#/SS0#		
26		P22	MTIOC3B/MTCLKC/TMO0	SCK0		
27		P21	MTIOC1B/TMC10	RXD0/SMISO0/SSCL0		
28		P20	MTIOC1A/TMRI0	TXD0/SMOSI0/SSDA0		
29	(5V tolerant)	P17	MTIOC3A/MTIOC3B/TMO1/POE8#	SCK1/MISOA/SDA		IRQ7
30	(5V tolerant)	P16	MTIOC3C/MTIOC3D/TMO2	TXD1/SMOSI1/SSDA1/MOSIA/SCL		IRQ6/RTCOUT/ADTRG0#
31		P15	MTIOC0B/MTCLKB/TMC12	RXD1/SMISO1/SSCL1	TS5	IRQ5
32		P14	MTIOC3A/MTCLKA/TMRI2	CTS1#/RTS1#/SS1#	TS6	IRQ4
33	(5V tolerant)	P13	MTIOC0B/TMO3	SDA		IRQ3
34	(5V tolerant)	P12	TMC11	SCL		IRQ2
35		PH3	TMC10		TS7	
36		PH2	TMRI0		TS8	IRQ1
37		PH1	TMO0		TS9	IRQ0
38		PH0			TS10	CACREF
39		P55	MTIOC4D/TMO3		TS11	
40		P54	MTIOC4B/TMC11		TS12	
41		P53				
42		P52		PMC1		
43		P51		PMC0		
44		P50				
45		PC7	MTIOC3A/MTCLKB/TMO2	TXD8/SMOSI8/SSDA8/MISOA	TS13	CACREF
46		PC6	MTIOC3C/MTCLKA/TMC12	RXD8/SMISO8/SSCL8/MOSIA	TS14	
47		PC5	MTIOC3B/MTCLKD/TMRI2	SCK8/RSPCKA	TS15	
48		PC4	MTIOC3D/MTCLKC/TMC11/POE0#	SCK5/CTS8#/RTS8#/SS8#/SSLA0	TSCAP	
49		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5	TS16	
50		PC2	MTIOC4B	RXD5/SMISO5/SSCL5/SSLA3	TS17	
51		PC1	MTIOC3A	SCK5/SSLA2		
52		PC0	MTIOC3C	CTS5#/RTS5#/SS5#/SSLA1		

Table 1.7 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIg, SCIf, RSPI, IIC)	Touch sensing	Others
49		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/SSCL12	TS35	IRQ7/AN018/CVREFB0
50		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/SMOSI12/SSDA12		AN017/CMPB0
51		PE0		SCK12		AN016
52		P47*1				AN007
53		P46*1				AN006
54		P45*1				AN005
55		P44*1				AN004
56		P43*1				AN003
57		P42*1				AN002
58		P41*1				AN001
59	VREFL0	PJ7*1				
60		P40*1				AN000
61	VREFH0	PJ6*1				
62	AVCC0					
63		P05*1				DA1
64	AVSS0					

Note 1. The power source of the I/O buffer for these pins is AVCC0.

Note 2. PC0 and PC1 are valid only when the port switching function is selected.

4.1 I/O Register Addresses (Address Order)

Table 4.1 List of I/O Registers (Address Order) (1 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
0008 0000h	SYSTEM	Mode Monitor Register	MDMONR	16	16	3 ICLK
0008 0008h	SYSTEM	System Control Register 1	SYSCR1	16	16	3 ICLK
0008 000Ch	SYSTEM	Standby Control Register	SBYCR	16	16	3 ICLK
0008 0010h	SYSTEM	Module Stop Control Register A	MSTPCRA	32	32	3 ICLK
0008 0014h	SYSTEM	Module Stop Control Register B	MSTPCRB	32	32	3 ICLK
0008 0018h	SYSTEM	Module Stop Control Register C	MSTPCRC	32	32	3 ICLK
0008 001Ch	SYSTEM	Module Stop Control Register D	MSTPCRD	32	32	3 ICLK
0008 0020h	SYSTEM	System Clock Control Register	SCKCR	32	32	3 ICLK
0008 0026h	SYSTEM	System Clock Control Register 3	SCKCR3	16	16	3 ICLK
0008 0028h	SYSTEM	PLL Control Register	PLLCR	16	16	3 ICLK
0008 002Ah	SYSTEM	PLL Control Register 2	PLLCR2	8	8	3 ICLK
0008 0032h	SYSTEM	Main Clock Oscillator Control Register	MOSCCR	8	8	3 ICLK
0008 0033h	SYSTEM	Sub-Clock Oscillator Control Register	SOSCCR	8	8	3 ICLK
0008 0034h	SYSTEM	Low-Speed On-Chip Oscillator Control Register	LOCOCR	8	8	3 ICLK
0008 0035h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Control Register	ILOCOCR	8	8	3 ICLK
0008 0036h	SYSTEM	High-Speed On-Chip Oscillator Control Register	HOCOCR	8	8	3 ICLK
0008 003Ch	SYSTEM	Oscillation Stabilization Flag Register	OSCOVFSR	8	8	3 ICLK
0008 003Dh	SYSTEM	High-Speed On-Chip Oscillator Forced Oscillation Control Register	HOFCR	8	8	3 ICLK
0008 003Eh	SYSTEM	CLKOUT Output Control Register	CKOCR	16	16	3 ICLK
0008 0040h	SYSTEM	Oscillation Stop Detection Control Register	OSTDCR	8	8	3 ICLK
0008 0041h	SYSTEM	Oscillation Stop Detection Status Register	OSTDSR	8	8	3 ICLK
0008 0060h	SYSTEM	Low-Speed On-Chip Oscillator Trimming Register	LOCOTRR	8	8	3 ICLK
0008 0064h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Trimming Register	ILOCOTRR	8	8	3 ICLK
0008 0068h	SYSTEM	High-Speed On-Chip Oscillator Trimming Register 0	HOCOTRR0	8	8	3 ICLK
0008 00A0h	SYSTEM	Operating Power Control Register	OPCCR	8	8	3 ICLK
0008 00A1h	SYSTEM	Sleep Mode Return Clock Source Switching Register	RSTCKCR	8	8	3 ICLK
0008 00A2h	SYSTEM	Main Clock Oscillator Wait Control Register	MOSCWTCR	8	8	3 ICLK
0008 00AAh	SYSTEM	Sub Operating Power Control Register	SOPCCR	8	8	3 ICLK
0008 00B0h	LPT	Low-Power Timer Control Register 1	LPTCR1	8	8	3 ICLK
0008 00B1h	LPT	Low-Power Timer Control Register 2	LPTCR2	8	8	3 ICLK
0008 00B2h	LPT	Low-Power Timer Control Register 3	LPTCR3	8	8	3 ICLK
0008 00B4h	LPT	Low-Power Timer Cycle Setting Register	LPTPRD	16	16	3 ICLK
0008 00B8h	LPT	Low-Power Timer Compare Register 0	LPCMR0	16	16	3 ICLK
0008 00BCh	LPT	Low-Power Timer Standby Wakeup Enable Register	LPWUCR	16	16	3 ICLK
0008 00C0h	SYSTEM	Reset Status Register 2	RSTSR2	8	8	3 ICLK
0008 00C2h	SYSTEM	Software Reset Register	SWRR	16	16	3 ICLK
0008 00E0h	SYSTEM	Voltage Monitoring 1 Circuit Control Register 1	LVD1CR1	8	8	3 ICLK
0008 00E1h	SYSTEM	Voltage Monitoring 1 Circuit Status Register	LVD1SR	8	8	3 ICLK
0008 00E2h	SYSTEM	Voltage Monitoring 2 Circuit Control Register 1	LVD2CR1	8	8	3 ICLK
0008 00E3h	SYSTEM	Voltage Monitoring 2 Circuit Status Register	LVD2SR	8	8	3 ICLK
0008 03FEh	SYSTEM	Protect Register	PRCR	16	16	3 ICLK
0008 1300h	BSC	Bus Error Status Clear Register	BERCLR	8	8	2 ICLK
0008 1304h	BSC	Bus Error Monitoring Enable Register	BEREN	8	8	2 ICLK
0008 1308h	BSC	Bus Error Status Register 1	BERSR1	8	8	2 ICLK
0008 130Ah	BSC	Bus Error Status Register 2	BERSR2	16	16	2 ICLK
0008 1310h	BSC	Bus Priority Control Register	BUSPRI	16	16	2 ICLK
0008 2400h	DTC	DTC Control Register	DTCCR	8	8	2 ICLK
0008 2404h	DTC	DTC Vector Base Register	DTCVBR	32	32	2 ICLK
0008 2408h	DTC	DTC Address Mode Register	DTCADMOD	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (9 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
0008 A0A6h	SMCI5	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A0A7h	SCI5	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A0A8h	SCI5	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A0A9h	SCI5	I ² C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A0AAh	SCI5	I ² C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A0ABh	SCI5	I ² C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A0ACh	SCI5	I ² C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A0ADh	SCI5	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 A0AEh	SCI5	Transmit Data Register HL	TDRHL	16	16	2 or 3 PCLKB
0008 A0AEh	SCI5	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB
0008 A0AFh	SCI5	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB
0008 A0B0h	SCI5	Receive Data Register HL	RDRHL	16	16	2 or 3 PCLKB
0008 A0B0h	SCI5	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB
0008 A0B1h	SCI5	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB
0008 A0B2h	SCI5	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB
0008 A0C0h	SCI6	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A0C1h	SCI6	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A0C2h	SCI6	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A0C3h	SCI6	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A0C4h	SCI6	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A0C5h	SCI6	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A0C6h	SMCI6	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A0C7h	SCI6	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A0C8h	SCI6	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A0C9h	SCI6	I ² C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A0CAh	SCI6	I ² C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A0CBh	SCI6	I ² C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A0CCh	SCI6	I ² C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A0CDh	SCI6	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 A0CEh	SCI6	Transmit Data Register HL	TDRHL	16	16	2 or 3 PCLKB
0008 A0CEh	SCI6	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB
0008 A0CFh	SCI6	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB
0008 A0D0h	SCI6	Receive Data Register HL	RDRHL	16	16	2 or 3 PCLKB
0008 A0D0h	SCI6	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB
0008 A0D1h	SCI6	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB
0008 A0D2h	SCI6	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB
0008 A100h	SCI8	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A101h	SCI8	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A102h	SCI8	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A103h	SCI8	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A104h	SCI8	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A105h	SCI8	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A106h	SMCI8	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A107h	SCI8	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A108h	SCI8	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A109h	SCI8	I ² C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A10Ah	SCI8	I ² C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A10Bh	SCI8	I ² C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A10Ch	SCI8	I ² C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A10Dh	SCI8	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 A10Eh	SCI8	Transmit Data Register HL	TDRHL	16	16	2 or 3 PCLKB
0008 A10Eh	SCI8	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (13 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
0008 C065h	PORT5	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Ah	PORTA	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Bh	PORTB	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Ch	PORTC	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Dh	PORTD	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C06Eh	PORTE	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C071h	PORTH	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C072h	PORTJ	Port Mode Register	PMR	8	8	2 or 3 PCLKB
0008 C082h	PORT1	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C083h	PORT1	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C084h	PORT2	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C085h	PORT2	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C086h	PORT3	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C087h	PORT3	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C094h	PORTA	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C095h	PORTA	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C096h	PORTB	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C097h	PORTB	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C098h	PORTC	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C099h	PORTC	Open Drain Control Register 1	ODR1	8	8	2 or 3 PCLKB
0008 C09Ah	PORTD	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C09Ch	PORTE	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C0A4h	PORTJ	Open Drain Control Register 0	ODR0	8	8	2 or 3 PCLKB
0008 C0C0h	PORT0	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C1h	PORT1	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C2h	PORT2	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C3h	PORT3	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C4h	PORT4	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0C5h	PORT5	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CAh	PORTA	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CBh	PORTB	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CCh	PORTC	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CDh	PORTD	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0CEh	PORTE	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0D1h	PORTH	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0D2h	PORTJ	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB
0008 C0E1h	PORT1	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0E2h	PORT2	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0E3h	PORT3	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0E5h	PORT5	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0EAh	PORTA	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0EBh	PORTB	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0ECh	PORTC	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0EDh	PORTD	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0EEh	PORTE	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0F1h	PORTH	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C0F2h	PORTJ	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB
0008 C11Fh	MPC	Write-Protect Register	PWPR	8	8	2 or 3 PCLKB
0008 C120h	PORT	Port Switching Register B	PSRB	8	8	2 or 3 PCLKB
0008 C121h	PORT	Port Switching Register A	PSRA	8	8	2 or 3 PCLKB
0008 C143h	MPC	P03 Pin Function Control Register	P03PFS	8	8	2 or 3 PCLKB
0008 C145h	MPC	P05 Pin Function Control Register	P05PFS	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (14 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
0008 C147h	MPC	P07 Pin Function Control Register	P07PFS	8	8	2 or 3 PCLKB
0008 C14Ah	MPC	P12 Pin Function Control Register	P12PFS	8	8	2 or 3 PCLKB
0008 C14Bh	MPC	P13 Pin Function Control Register	P13PFS	8	8	2 or 3 PCLKB
0008 C14Ch	MPC	P14 Pin Function Control Register	P14PFS	8	8	2 or 3 PCLKB
0008 C14Dh	MPC	P15 Pin Function Control Register	P15PFS	8	8	2 or 3 PCLKB
0008 C14Eh	MPC	P16 Pin Function Control Register	P16PFS	8	8	2 or 3 PCLKB
0008 C14Fh	MPC	P17 Pin Function Control Register	P17PFS	8	8	2 or 3 PCLKB
0008 C150h	MPC	P20 Pin Function Control Register	P20PFS	8	8	2 or 3 PCLKB
0008 C151h	MPC	P21 Pin Function Control Register	P21PFS	8	8	2 or 3 PCLKB
0008 C152h	MPC	P22 Pin Function Control Register	P22PFS	8	8	2 or 3 PCLKB
0008 C153h	MPC	P23 Pin Function Control Register	P23PFS	8	8	2 or 3 PCLKB
0008 C154h	MPC	P24 Pin Function Control Register	P24PFS	8	8	2 or 3 PCLKB
0008 C155h	MPC	P25 Pin Function Control Register	P25PFS	8	8	2 or 3 PCLKB
0008 C156h	MPC	P26 Pin Function Control Register	P26PFS	8	8	2 or 3 PCLKB
0008 C157h	MPC	P27 Pin Function Control Register	P27PFS	8	8	2 or 3 PCLKB
0008 C158h	MPC	P30 Pin Function Control Register	P30PFS	8	8	2 or 3 PCLKB
0008 C159h	MPC	P31 Pin Function Control Register	P31PFS	8	8	2 or 3 PCLKB
0008 C15Ah	MPC	P32 Pin Function Control Register	P32PFS	8	8	2 or 3 PCLKB
0008 C15Bh	MPC	P33 Pin Function Control Register	P33PFS	8	8	2 or 3 PCLKB
0008 C15Ch	MPC	P34 Pin Function Control Register	P34PFS	8	8	2 or 3 PCLKB
0008 C160h	MPC	P40 Pin Function Control Register	P40PFS	8	8	2 or 3 PCLKB
0008 C161h	MPC	P41 Pin Function Control Register	P41PFS	8	8	2 or 3 PCLKB
0008 C162h	MPC	P42 Pin Function Control Register	P42PFS	8	8	2 or 3 PCLKB
0008 C163h	MPC	P43 Pin Function Control Register	P43PFS	8	8	2 or 3 PCLKB
0008 C164h	MPC	P44 Pin Function Control Register	P44PFS	8	8	2 or 3 PCLKB
0008 C165h	MPC	P45 Pin Function Control Register	P45PFS	8	8	2 or 3 PCLKB
0008 C166h	MPC	P46 Pin Function Control Register	P46PFS	8	8	2 or 3 PCLKB
0008 C167h	MPC	P47 Pin Function Control Register	P47PFS	8	8	2 or 3 PCLKB
0008 C169h	MPC	P51 Pin Function Control Register	P51PFS	8	8	2 or 3 PCLKB
0008 C16Ah	MPC	P52 Pin Function Control Register	P52PFS	8	8	2 or 3 PCLKB
0008 C16Ch	MPC	P54 Pin Function Control Register	P54PFS	8	8	2 or 3 PCLKB
0008 C16Dh	MPC	P55 Pin Function Control Register	P55PFS	8	8	2 or 3 PCLKB
0008 C190h	MPC	PA0 Pin Function Control Register	PA0PFS	8	8	2 or 3 PCLKB
0008 C191h	MPC	PA1 Pin Function Control Register	PA1PFS	8	8	2 or 3 PCLKB
0008 C192h	MPC	PA2 Pin Function Control Register	PA2PFS	8	8	2 or 3 PCLKB
0008 C193h	MPC	PA3 Pin Function Control Register	PA3PFS	8	8	2 or 3 PCLKB
0008 C194h	MPC	PA4 Pin Function Control Register	PA4PFS	8	8	2 or 3 PCLKB
0008 C195h	MPC	PA5 Pin Function Control Register	PA5PFS	8	8	2 or 3 PCLKB
0008 C196h	MPC	PA6 Pin Function Control Register	PA6PFS	8	8	2 or 3 PCLKB
0008 C197h	MPC	PA7 Pin Function Control Register	PA7PFS	8	8	2 or 3 PCLKB
0008 C198h	MPC	PB0 Pin Function Control Register	PB0PFS	8	8	2 or 3 PCLKB
0008 C199h	MPC	PB1 Pin Function Control Register	PB1PFS	8	8	2 or 3 PCLKB
0008 C19Ah	MPC	PB2 Pin Function Control Register	PB2PFS	8	8	2 or 3 PCLKB
0008 C19Bh	MPC	PB3 Pin Function Control Register	PB3PFS	8	8	2 or 3 PCLKB
0008 C19Ch	MPC	PB4 Pin Function Control Register	PB4PFS	8	8	2 or 3 PCLKB
0008 C19Dh	MPC	PB5 Pin Function Control Register	PB5PFS	8	8	2 or 3 PCLKB
0008 C19Eh	MPC	PB6 Pin Function Control Register	PB6PFS	8	8	2 or 3 PCLKB
0008 C19Fh	MPC	PB7 Pin Function Control Register	PB7PFS	8	8	2 or 3 PCLKB
0008 C1A0h	MPC	PC0 Pin Function Control Register	PC0PFS	8	8	2 or 3 PCLKB
0008 C1A1h	MPC	PC1 Pin Function Control Register	PC1PFS	8	8	2 or 3 PCLKB
0008 C1A2h	MPC	PC2 Pin Function Control Register	PC2PFS	8	8	2 or 3 PCLKB
0008 C1A3h	MPC	PC3 Pin Function Control Register	PC3PFS	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (18 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
007F C0B2h	FLASH	Flash Access Window Start Address Monitor Register	FAWSMR	16	16	2 or 3 FCLK
007F C0B4h	FLASH	Flash Access Window End Address Monitor Register	FAWEMR	16	16	2 or 3 FCLK
007F C0B6h	FLASH	Flash Initial Setting Register	FISR	8	8	2 or 3 FCLK
007F C0B7h	FLASH	Flash Extra Area Control Register	FEXCR	8	8	2 or 3 FCLK
007F C0B8h	FLASH	Flash Error Address Monitor Register L	FEAML	16	16	2 or 3 FCLK
007F C0BAh	FLASH	Flash Error Address Monitor Register H	FEAMH	8	8	2 or 3 FCLK
007F C0C0h	FLASH	Protection Unlock Register	FPR	8	8	2 or 3 FCLK
007F C0C1h	FLASH	Protection Unlock Status Register	FPSR	8	8	2 or 3 FCLK
007F C0C2h	FLASH	Flash Read Buffer Register L	FRBL	16	16	2 or 3 FCLK
007F C0C4h	FLASH	Flash Read Buffer Register H	FRBH	16	16	2 or 3 FCLK
007F FF80h	FLASH	Flash P/E Mode Control Register	FPMCR	8	8	2 or 3 FCLK
007F FF81h	FLASH	Flash Area Select Register	FASR	8	8	2 or 3 FCLK
007F FF82h	FLASH	Flash Processing Start Address Register L	FSARL	16	16	2 or 3 FCLK
007F FF84h	FLASH	Flash Processing Start Address Register H	FSARH	8	8	2 or 3 FCLK
007F FF85h	FLASH	Flash Control Register	FCR	8	8	2 or 3 FCLK
007F FF86h	FLASH	Flash Processing End Address Register L	FEARL	16	16	2 or 3 FCLK
007F FF88h	FLASH	Flash Processing End Address Register H	FEARH	8	8	2 or 3 FCLK
007F FF89h	FLASH	Flash Reset Register	FRESETR	8	8	2 or 3 FCLK
007F FF8Ah	FLASH	Flash Status Register 0	FSTATR0	8	8	2 or 3 FCLK
007F FF8Bh	FLASH	Flash Status Register 1	FSTATR1	8	8	2 or 3 FCLK
007F FF8Ch	FLASH	Flash Write Buffer Register L	FWBL	16	16	2 or 3 FCLK
007F FF8Eh	FLASH	Flash Write Buffer Register H	FWBH	16	16	2 or 3 FCLK
007F FFB2h	FLASH	Flash P/E Mode Entry Register	FENTRYR	16	16	2 or 3 FCLK
007F FFB2h	CTSU	CTSU Reference Current Calibration Register	CTSUTMR	8	8	2 or 3 FCLK

Table 5.4 DC Characteristics (2)

Conditions: $1.8\text{ V} \leq V_{CC} = AVCC0 < 2.0\text{ V}$, $2.0\text{ V} \leq V_{CC} < 2.7\text{ V}$, $2.0\text{ V} \leq AVCC0 < 2.7\text{ V}$, $V_{SS} = AVSS0 = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P12, P13, P16, P17 (5 V tolerant)	V_{IH}	$V_{CC} \times 0.8$	—	5.8	V
	Ports P14, P15, Ports P20 to P27, Ports P30 to P37, Ports P50 to P55, Ports PA0 to PA7, Ports PB0 to PB7, Ports PC0 to PC7, Ports PD0 to PD7, Ports PE0 to PE7, Ports PH0 to PH3, Ports PJ1, PJ3, RES#	V_{IH}	$V_{CC} \times 0.8$	—	$V_{CC} + 0.3$	V
	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7	V_{IH}	$AVCC0 \times 0.8$	—	$AVCC0 + 0.3$	V
	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7	V_{IL}	-0.3	—	$AVCC0 \times 0.2$	V
	Ports other than above	V_{IL}	-0.3	—	$V_{CC} \times 0.2$	V
	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7	ΔV_T	$AVCC0 \times 0.01$	—	—	V
	Ports other than above	ΔV_T	$V_{CC} \times 0.01$	—	—	V
	Ports other than above	ΔV_T	$V_{CC} \times 0.01$	—	—	V
Input level voltage (except for Schmitt trigger input pins)	MD	V_{IH}	$V_{CC} \times 0.9$	—	$V_{CC} + 0.3$	V
	EXTAL (external clock input)	V_{IH}	$V_{CC} \times 0.8$	—	$V_{CC} + 0.3$	V
	MD	V_{IL}	-0.3	—	$V_{CC} \times 0.1$	V
	EXTAL (external clock input)	V_{IL}	-0.3	—	$V_{CC} \times 0.2$	V

Table 5.5 DC Characteristics (3)

Conditions: $1.8\text{ V} \leq V_{CC} = AVCC0 < 2.0\text{ V}$, $2.0\text{ V} \leq V_{CC} \leq 5.5\text{ V}$, $2.0\text{ V} \leq AVCC0 \leq 5.5\text{ V}$, $V_{SS} = AVSS0 = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35	$ I_{in} $	—	1.0	μA	$V_{in} = 0\text{ V}$, V_{CC}
Three-state leakage current (off-state)	Ports for 5-V tolerant	$ I_{TSL} $	—	1.0	μA	$V_{in} = 0\text{ V}$, 5.8V
	Ports except for 5 V tolerant	$ I_{TSL} $	—	0.2	μA	$V_{in} = 0\text{ V}$, V_{CC}
Input capacitance	All input pins (except for port P35)	C_{in}	—	15	pF	$V_{in} = 0\text{ mV}$, $f = 1\text{ MHz}$, $T_a = 25^\circ\text{C}$
	port P35	C_{in}	—	30	pF	$V_{in} = 0\text{ mV}$, $f = 1\text{ MHz}$, $T_a = 25^\circ\text{C}$

Table 5.6 DC Characteristics (4)

Conditions: $1.8\text{ V} \leq V_{CC} = AVCC0 < 2.0\text{ V}$, $2.0\text{ V} \leq V_{CC} < 5.5\text{ V}$, $2.0\text{ V} \leq AVCC0 < 5.5\text{ V}$, $V_{SS} = AVSS0 = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for port P35)	R_U	10	20	$k\Omega$	$V_{in} = 0\text{ V}$

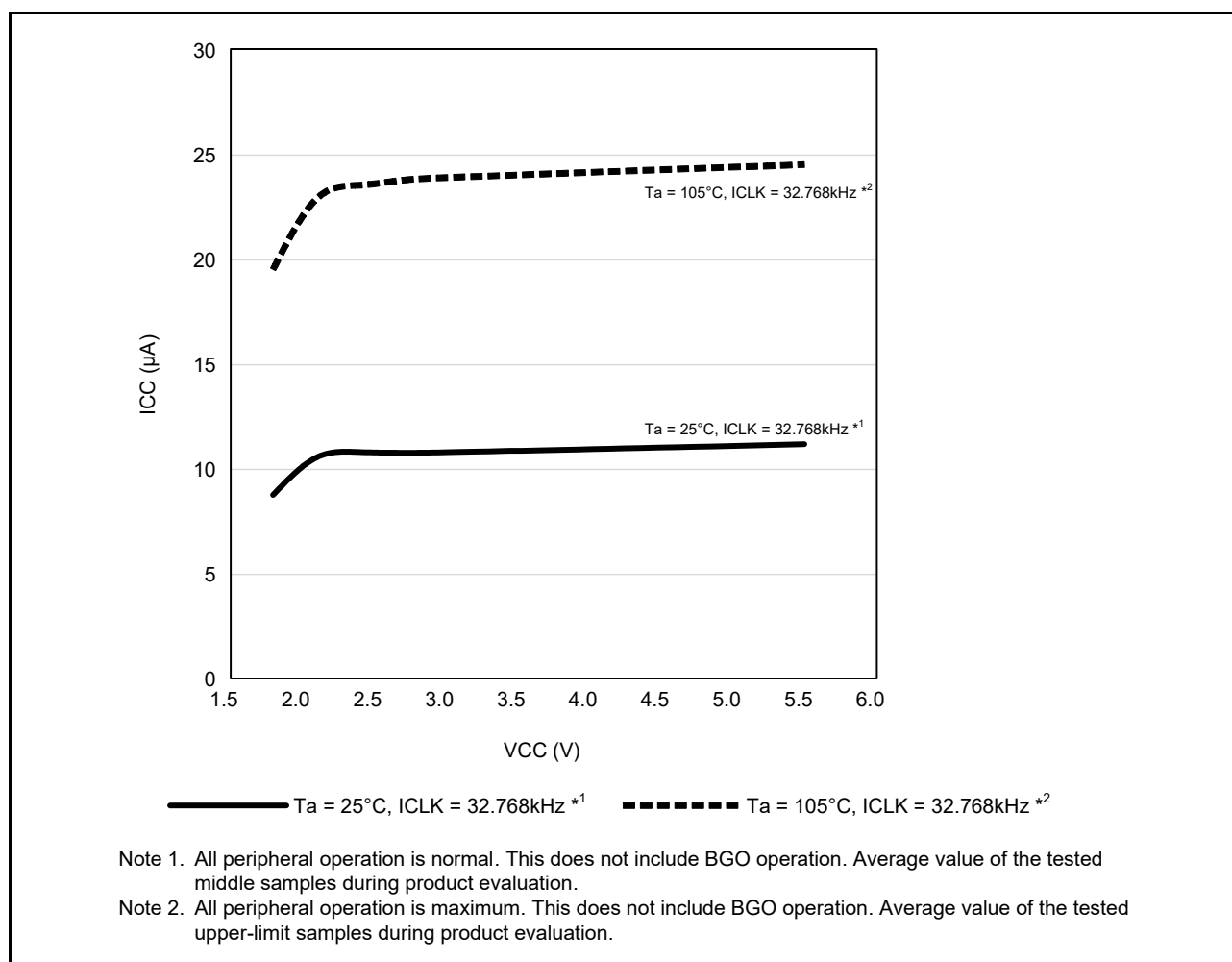


Figure 5.3 Voltage Dependency in Low-Speed Operating Mode (Reference Data)

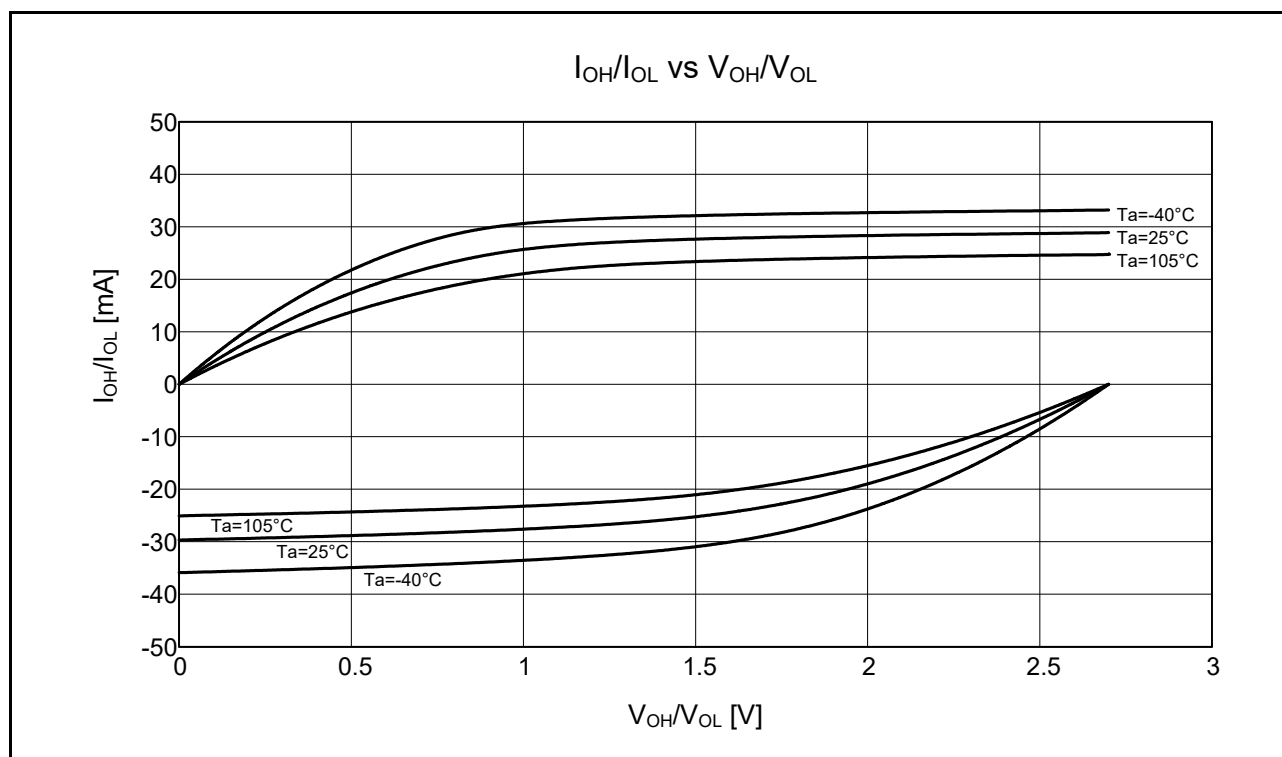


Figure 5.19 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at $V_{CC} = 2.7$ V When High-Drive Output is Selected (Reference Data)

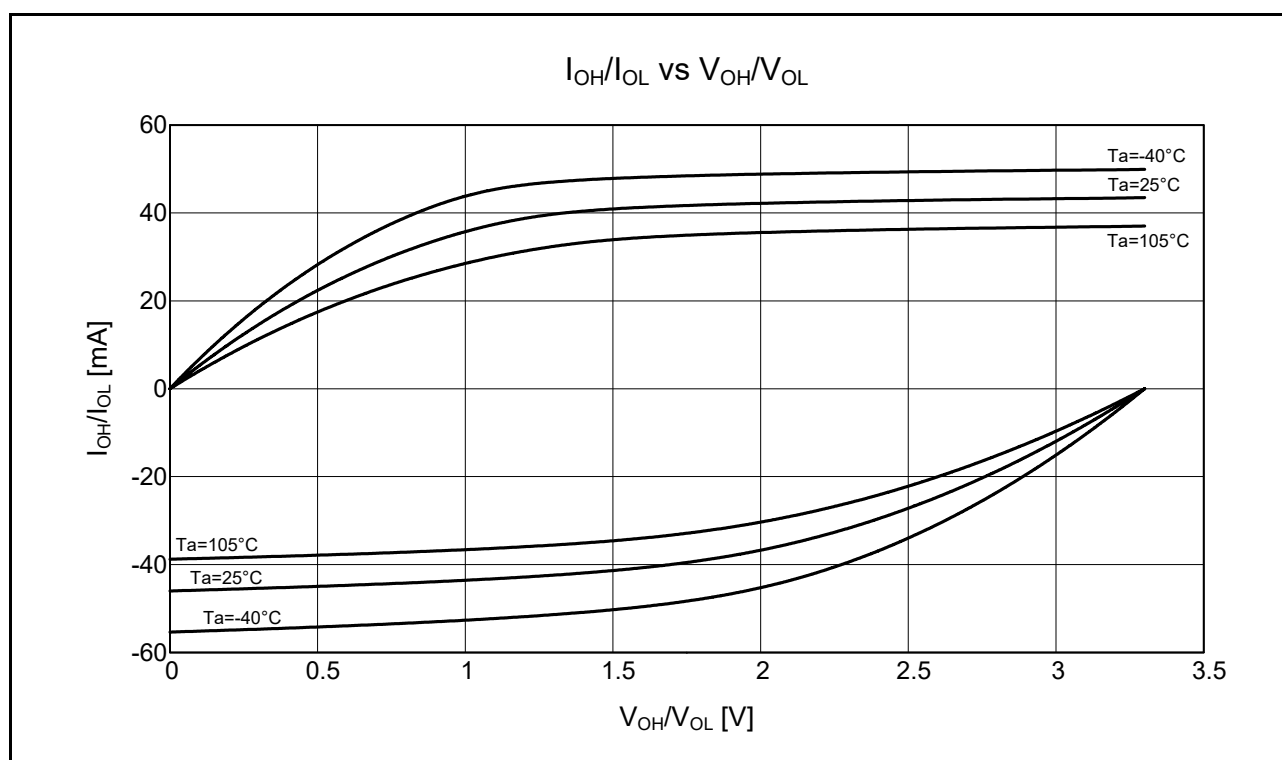


Figure 5.20 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at $V_{CC} = 3.3$ V When High-Drive Output is Selected (Reference Data)

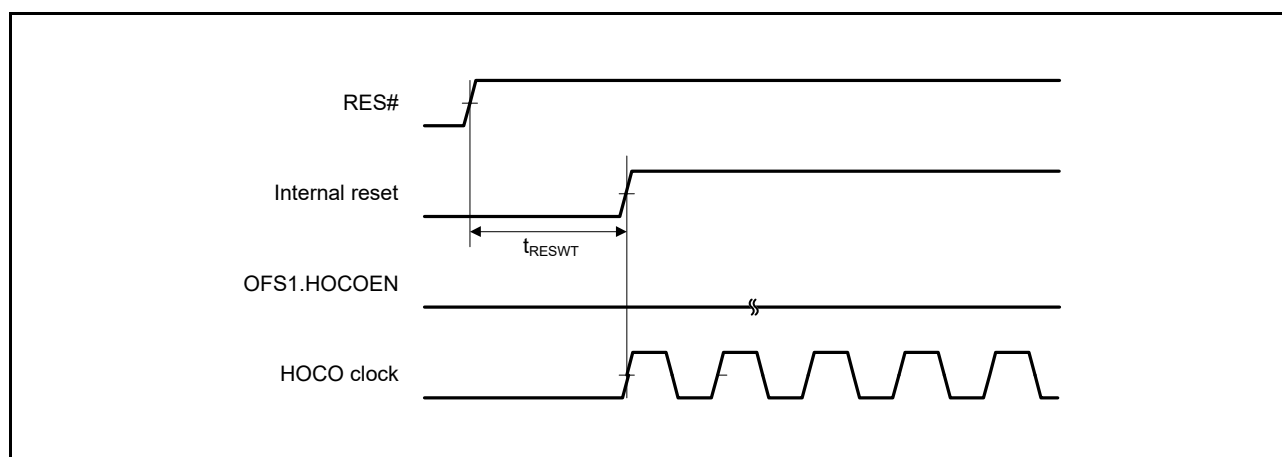


Figure 5.30 HOCO Clock Oscillation Start Timing (After Reset is Canceled by Setting OFS1.HOCOEN Bit to 0)

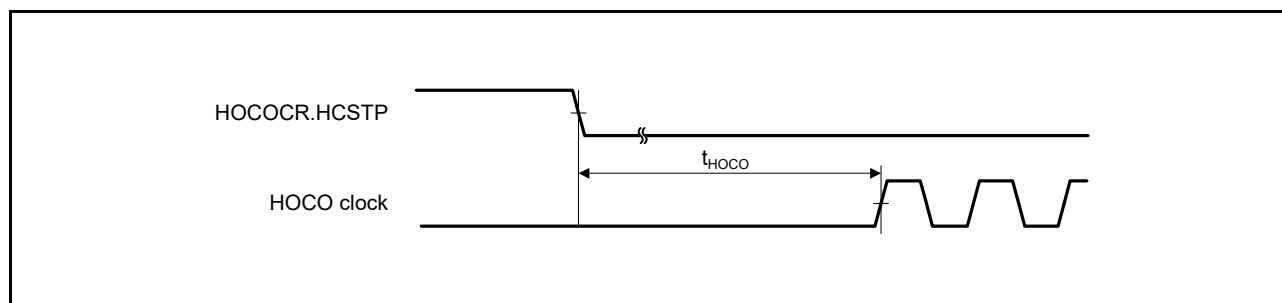


Figure 5.31 HOCO Clock Oscillation Start Timing (Oscillation is Started by Setting HOCOCR.HCSTP Bit)

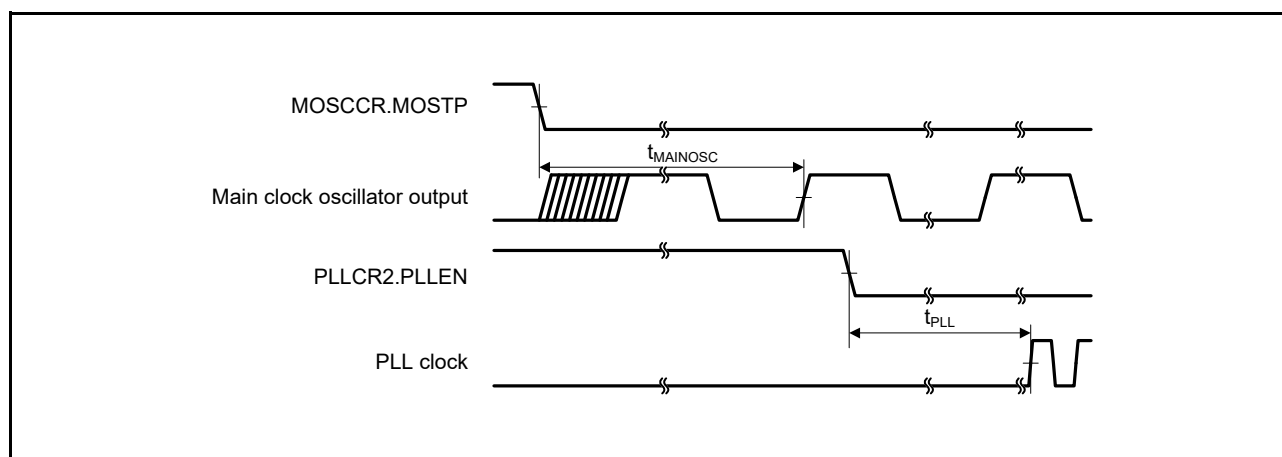


Figure 5.32 PLL Clock Oscillation Start Timing (PLL is Operated after Main Clock Oscillation Has Settled)

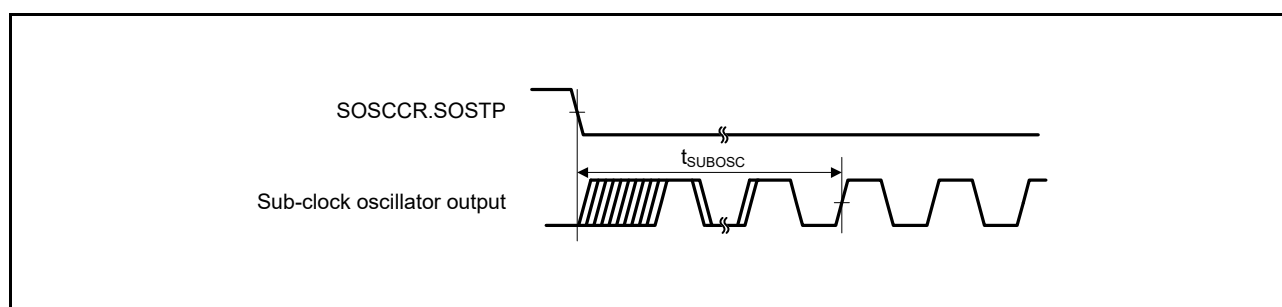


Figure 5.33 Sub-Clock Oscillation Start Timing

Table 5.33 Timing of On-Chip Peripheral Modules (1)

Conditions: $1.8\text{ V} \leq VCC = AVCC0 < 2.0\text{ V}$, $2.0\text{ V} \leq VCC \leq 5.5\text{ V}$, $2.0\text{ V} \leq AVCC0 \leq 5.5\text{ V}$, $VSS = AVSS0 = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item			Symbol	Min.	Max.	Unit *1	Test Conditions
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t _{Cyc}	62.5	—	ns	Figure 5.49
		VCC = 1.8 V or above		125			
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t _{CH}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t _{CL}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin output rise time	VCC = 2.7 V or above	t _{Cr}	—	12	ns	
		VCC = 1.8 V or above			25		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t _{Cf}	—	12	ns	
		VCC = 1.8 V or above			25		

Note 1. t_{Pcyc} : PCLK cycle

Note 2. t_{cac} : CAC count clock source cycle

Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSSEL[3:0] bits = 0000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).

Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSSEL[3:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.36 Timing of On-Chip Peripheral Modules (4)Conditions: $2.7\text{ V} \leq \text{VCC} \leq 5.5\text{ V}$, $2.7\text{ V} \leq \text{AVCC0} \leq 5.5\text{ V}$, $\text{VSS} = \text{AVSS0} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

	Item	Symbol	Min.*1, *2	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL cycle time	t_{SCL}	$6(12) \times t_{\text{IICcyc}} + 1300$	—	ns	Figure 5.55
	SCL high pulse width	t_{SCLH}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	SCL low pulse width	t_{SCLL}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	SCL, SDA rise time	t_{Sr}	—	1000	ns	
	SCL, SDA fall time	t_{Sf}	—	300	ns	
	SCL, SDA spike pulse removal time	t_{SP}	0	$1(4) \times t_{\text{IICcyc}}$	ns	
	SDA bus free time	t_{BUF}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	START condition hold time	t_{STAH}	$t_{\text{IICcyc}} + 300$	—	ns	
	Repeated START condition setup time	t_{STAS}	1000	—	ns	
	STOP condition setup time	t_{STOS}	1000	—	ns	
	Data setup time	t_{SDAS}	$t_{\text{IICcyc}} + 50$	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL cycle time	t_{SCL}	$6(12) \times t_{\text{IICcyc}} + 600$	—	ns	Figure 5.55
	SCL high pulse width	t_{SCLH}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	SCL low pulse width	t_{SCLL}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	SCL, SDA rise time	t_{Sr}	—	300	ns	
	SCL, SDA fall time	t_{Sf}	—	300	ns	
	SCL, SDA spike pulse removal time	t_{SP}	0	$1(4) \times t_{\text{IICcyc}}$	ns	
	SDA bus free time	t_{BUF}	$3(6) \times t_{\text{IICcyc}} + 300$	—	ns	
	START condition hold time	t_{STAH}	$t_{\text{IICcyc}} + 300$	—	ns	
	Repeated START condition setup time	t_{STAS}	300	—	ns	
	STOP condition setup time	t_{STOS}	300	—	ns	
	Data setup time	t_{SDAS}	$t_{\text{IICcyc}} + 50$	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	

Note: t_{IICcyc} : RIIC internal reference count clock (IIC ϕ) cycle

Note 1. The value in parentheses is used when the ICMR3.NF[1:0] bits are set to 11b while a digital filter is enabled with the ICFER.NFE bit = 1.

Note 2. C_b is the total capacitance of the bus lines.

5.4 A/D Conversion Characteristics

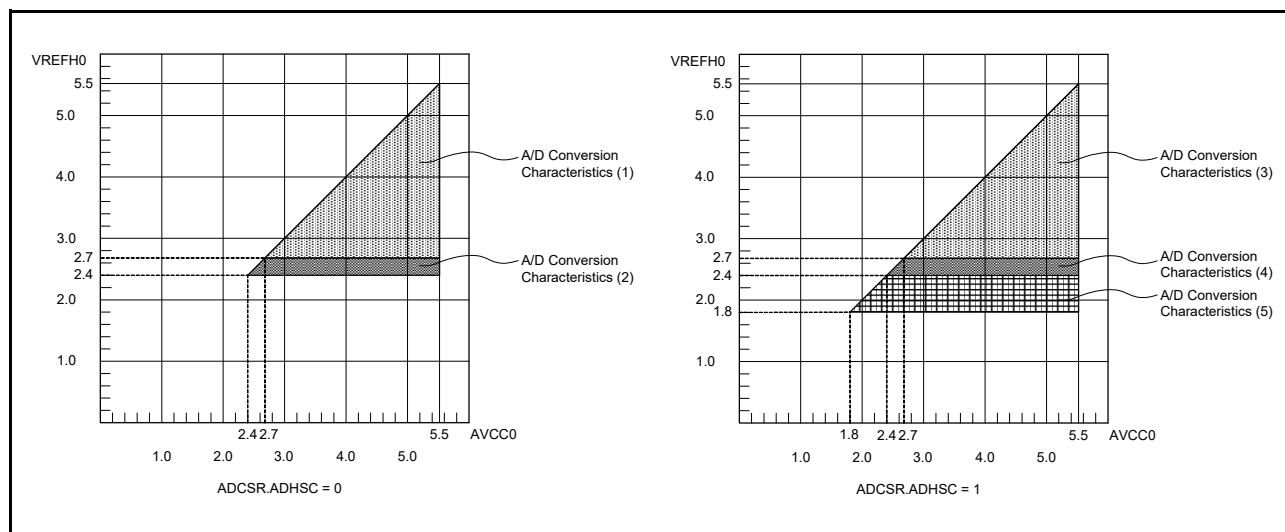


Figure 5.56 AVCC0 to VREFH0 Voltage Range

Table 5.40 A/D Conversion Characteristics (2)

Conditions: $2.4\text{ V} \leq V_{CC} \leq 5.5\text{ V}$, $2.4\text{ V} \leq AV_{CC0} \leq 5.5\text{ V}$, $2.4\text{ V} \leq V_{REFH0} \leq AV_{CC0}$, Reference voltage = V_{REFH0} ,
 $V_{SS} = AV_{SS0} = V_{REFL0} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	16	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance (Max.) = 1.3 kΩ	2.82	—	—	μs	High-precision channel ADCSR.ADHSC bit = 0 ADSSTRn = 0Dh
		4.5	—	—	μs	Normal-precision channel ADCSR.ADHSC bit = 0 ADSSTRn = 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included
Analog input resistance	Rs	—	—	2.5	kΩ	
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±4.5	LSB	
Full-scale error		—	±0.75	±4.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.0	±4.5	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

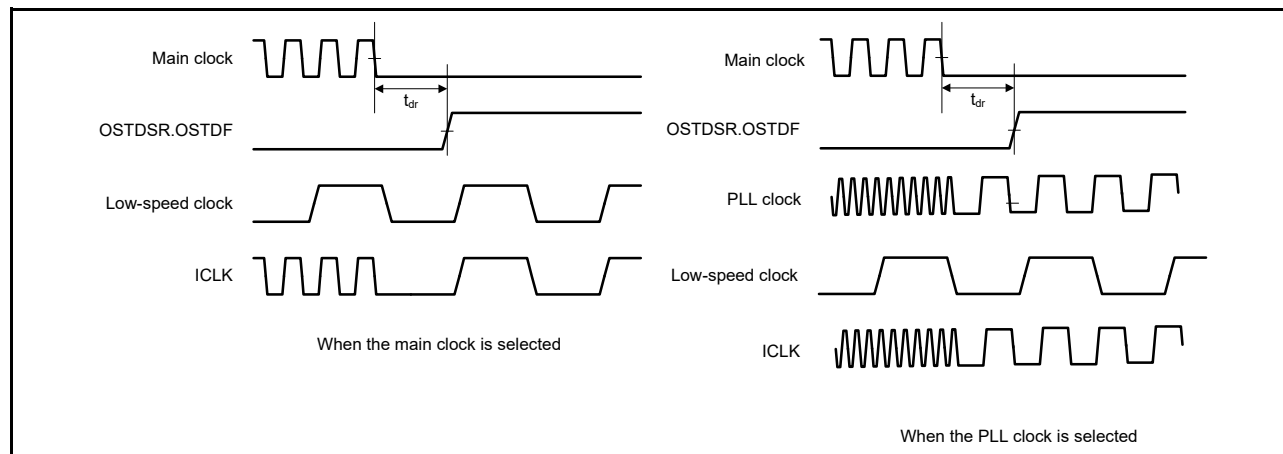
Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

5.10 Oscillation Stop Detection Timing

Table 5.51 Oscillation Stop Detection Timing

Conditions: $1.8\text{ V} \leq VCC = AVCC0 < 2.0\text{ V}$, $2.0\text{ V} \leq VCC \leq 5.5\text{ V}$, $2.0\text{ V} \leq AVCC0 \leq 5.5\text{ V}$, $VSS = AVSS0 = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	t_{dr}	—	—	1	ms	Figure 5.66

**Figure 5.66 Oscillation Stop Detection Timing**

5.12 E2 DataFlash Characteristics (Flash Memory for Data Storage)

Table 5.55 E2 DataFlash Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N _{DPEC}	100000	1000000	—	Times	
Data retention	After 10000 times of N _{DPEC}	t _{DDRP}	20*2, *3	—	—	Year	T _a = +85°C
	After 100000 times of N _{DPEC}		5*2, *3	—	—	Year	
	After 1000000 times of N _{DPEC}		—	1*2, *3	—	Year	T _a = +25°C

Note 1. The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1000 times for different addresses in 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).

Note 2. Characteristic when using the flash memory programmer and the self-programming library provided from Renesas Electronics.

Note 3. These results are obtained from reliability testing.

Table 5.56 E2 DataFlash Characteristics (2): high-speed operating mode

Conditions: 2.7 V ≤ VCC ≤ 5.5 V, 2.7 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V

Temperature range for the programming/erasure operation: T_a = −40 to +105°C

Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	1-byte	t _{DP1}	—	86	761	—	40.5	374	μs
Erasure time	1-Kbyte	t _{DE1K}	—	17.4	456	—	6.15	228	ms
	8-Kbyte	t _{DE8K}	—	60.4	499	—	9.3	231	ms
Blank check time	1-byte	t _{DBC1}	—	—	48	—	—	15.9	μs
	1-Kbyte	t _{DBC1K}	—	—	1.58	—	—	0.127	μs
Erase operation forcible stop time		t _{DSED}	—	—	21.5	—	—	12.8	μs
DataFlash STOP recovery time		t _{DSTOP}	5.0	—	—	5	—	—	μs

Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.

Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: The frequency accuracy of FCLK should be ±3.5%.

Table 5.57 E2 DataFlash Characteristics (3): middle-speed operating mode

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V

Temperature range for the programming/erasure operation: T_a = −40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	1-byte	t _{DP1}	—	126	1160	—	85.4	818	μs
Erasure time	1-Kbyte	t _{DE1K}	—	17.5	457	—	7.76	259	ms
	8-Kbyte	t _{DE8K}	—	60.5	500	—	4.2	66.9	ms
Blank check time	1-byte	t _{DBC1}	—	—	78	—	—	50	μs
	1-Kbyte	t _{DBC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t _{DSED}	—	—	33.5	—	—	25.5	μs
DataFlash STOP recovery time		t _{DSTOP}	720	—	—	720	—	—	ns

Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.

Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: The frequency accuracy of FCLK should be ±3.5%.

NOTES FOR CMOS DEVICES

- (1) **VOLTAGE APPLICATION WAVEFORM AT INPUT PIN:** Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).
- (2) **HANDLING OF UNUSED INPUT PINS:** Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.
- (3) **PRECAUTION AGAINST ESD:** A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.
- (4) **STATUS BEFORE INITIALIZATION:** Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.
- (5) **POWER ON/OFF SEQUENCE:** In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.
- (6) **INPUT OF SIGNAL DURING POWER OFF STATE :** Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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